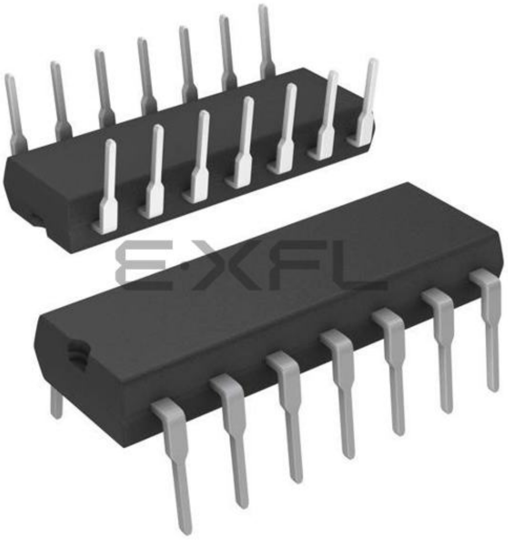

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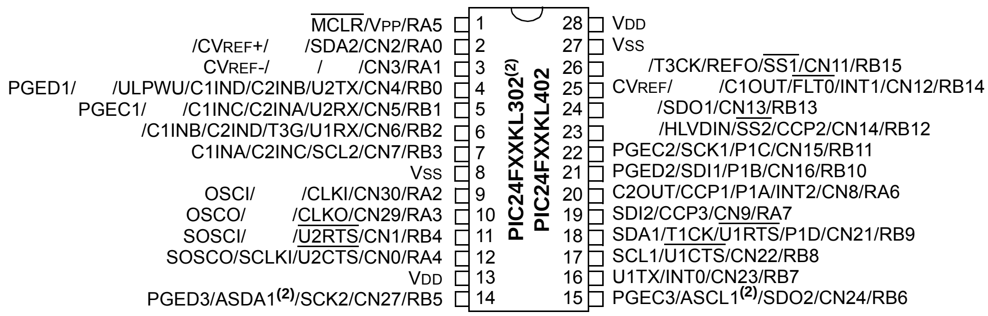
Applications of "Embedded - Microcontrollers"

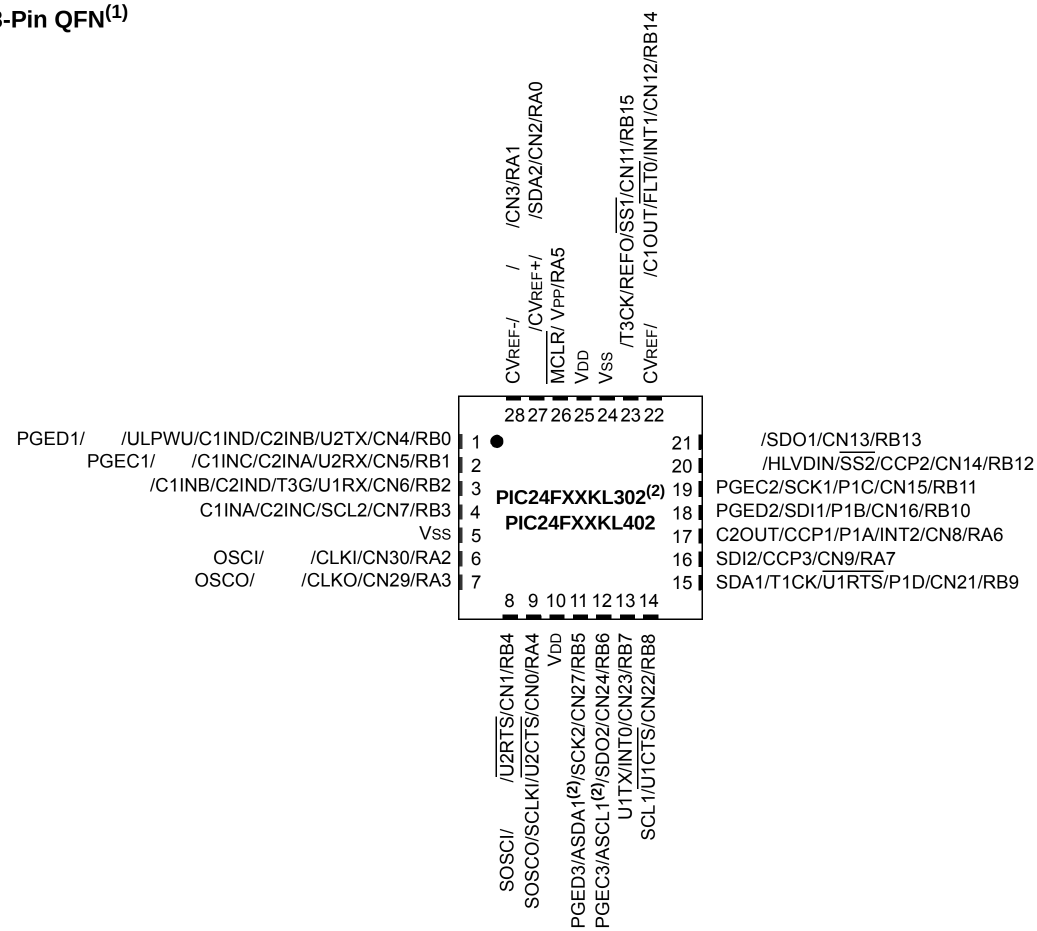
Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	12
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	14-DIP (0.300", 7.62mm)
Supplier Device Package	14-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08kl200-e-p

Pin Diagrams: PIC24FXXKL302/402

28-Pin SPDIP/SSOP/SOIC(1)



28-Pin QFN(1)



Contact your Microchip sales team for Chip Scale Package (CSP) availability.

Note 1: Analog features (indicated in) are not available on PIC24FXXKL302 devices.
2: Alternate location for I2C™ functionality of MSSP1, as determined by the I2C1SEL Configuration bit.

TABLE 1-5: PIC24F16KL20X/10X FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Buffer	Description
	20-Pin PDIP/ SSOP/ SOIC	20-Pin QFN	14-Pin PDIP/ TSSOP			
SCK1	15	12	8	I/O	ST	MSSP1 SPI Serial Input/Output Clock
SCL1	12	9	8	I/O	I^2C	MSSP1 I^2C Clock Input/Output
SCLKI	10	7	12	I	ST	Digital Secondary Clock Input
SDA1	13	10	9	I/O	I^2C	MSSP1 I^2C Data Input/Output
SDI1	17	14	11	I	ST	MSSP1 SPI Serial Data Input
SDO1	16	13	9	O	—	MSSP1 SPI Serial Data Output
SOSCI	9	6	11	I	ANA	Secondary Oscillator Input
SOSCO	10	7	12	O	ANA	Secondary Oscillator Output
$\overline{\text{SS1}}$	12	9	12	O	—	SPI1 Slave Select
T1CK	13	10	9	I	ST	Timer1 Clock
T3CK	18	15	12	I	ST	Timer3 Clock
T3G	6	3	11	I	ST	Timer3 External Gate Input
$\overline{\text{U1CTS}}$	12	9	8	I	ST	UART1 Clear-to-Send Input
$\overline{\text{U1RTS}}$	13	10	9	O	—	UART1 Request-to-Send Output
U1RX	6	3	12	I	ST	UART1 Receive
U1TX	11	8	11	O	—	UART1 Transmit
ULPWU	3	1	3	I	ANA	Ultra Low-Power Wake-up Input
VDD	20	17	14	P	—	Positive Supply for Peripheral Digital Logic and I/O Pins
VREF+	2	19	2	I	ANA	A/D Reference Voltage Input (+)
VREF-	3	20	3	I	ANA	A/D Reference Voltage Input (-)
VSS	19	16	13	P	—	Ground Reference for Logic and I/O Pins

Legend: TTL = TTL input buffer; ST = Schmitt Trigger input buffer; ANA = Analog level input/output; I^2C = I^2C™/SMBus input buffer

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT MICROCONTROLLERS

2.1 Basic Connection Requirements

Getting started with the PIC24F16KL402 family of 16-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Power Supply Pins"**)
- All AVDD and AVSS pins, regardless of whether or not the analog device features are used (see **Section 2.2 "Power Supply Pins"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.3 "Master Clear (MCLR) Pin"**)

These pins must also be connected if they are being used in the end application:

- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.4 "ICSP Pins"**)
- OSCI and OSCO pins when an external oscillator source is used (see **Section 2.5 "External Oscillator Pins"**)

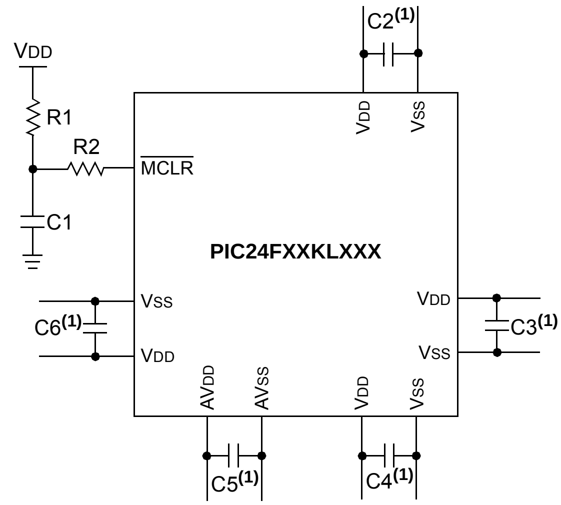
Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

Note:	The AVDD and AVSS pins must always be connected, regardless of whether any of the analog modules are being used.

The minimum mandatory connections are shown in Figure 2-1.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



Key (all values are recommendations):

C1 through C6: 0.1 µF, 20V ceramic

R1: 10 kΩ

R2: 100Ω to 470Ω

Note 1: The example shown is for a PIC24F device with five VDD/VSS and AVDD/AVSS pairs. Other devices may have more or less pairs; adjust the number of decoupling capacitors appropriately.

5.2 RTSP Operation

The PIC24F Flash program memory array is organized into rows of 32 instructions or 96 bytes. RTSP allows the user to erase blocks of 1 row, 2 rows and 4 rows (32, 64 and 128 instructions) at a time, and to program one row at a time.

The 1-row (96 bytes), 2-row (192 bytes) and 4-row (384 bytes) erase blocks and single row write block (96 bytes) are edge-aligned, from the beginning of program memory.

When data is written to program memory using `TBLWT` instructions, the data is not written directly to memory. Instead, data written using Table Writes is stored in holding latches until the programming sequence is executed.

Any number of `TBLWT` instructions can be executed and a write will be successfully performed. However, 32 `TBLWT` instructions are required to write the full row of memory.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of `TBLWT` instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register.

Data can be loaded in any order and the holding registers can be written to multiple times before performing a write operation. Subsequent writes, however, will wipe out any previous writes.

Note:	Writing to a location multiple times without erasing it is not recommended.

All of the Table Write operations are single-word writes (two instruction cycles), because only the buffers are written. A programming cycle is required for programming each row.

5.3 Enhanced In-Circuit Serial Programming

Enhanced ICSP uses an on-board bootloader, known as the program executive, to manage the programming process. Using an SPI data frame format, the program executive can erase, program and verify program memory. For more information on Enhanced ICSP, see the device programming specification.

5.4 Control Registers

There are two SFRs used to read and write the program Flash memory: NVMCON and NVMKEY.

The NVMCON register (Register 5-1) controls the blocks that need to be erased, which memory type is to be programmed and when the programming cycle starts.

NVMKEY is a write-only register that is used for write protection. To start a programming or erase sequence, the user must consecutively write 55h and AAh to the NVMKEY register. For more information, refer to **Section 5.5 “Programming Operations”**.

5.5 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. During a programming or erase operation, the processor stalls (waits) until the operation is finished. Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

REGISTER 7-1: RCON: RESET CONTROL REGISTER(1)

R/W-0	R/W-0	R/W-0(3)	U-0	U-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	SBOREN	—	—	—	CM	PMSLP
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or an Uninitialized W register is used as an Address Pointer and caused a Reset
0 = An illegal opcode or Uninitialized W register Reset has not occurred

bit 13 **SBOREN:** Software Enable/Disable of BOR bit(3)
1 = BOR is turned on in software
0 = BOR is turned off in software

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CM:** Configuration Word Mismatch Reset Flag bit
1 = A Configuration Word Mismatch Reset has occurred
0 = A Configuration Word Mismatch Reset has not occurred

bit 8 **PMSLP:** Program Memory Power During Sleep bit
1 = Program memory bias voltage remains powered during Sleep
0 = Program memory bias voltage is powered down during Sleep

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.
2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.
3: The SBOREN bit is forced to '0' when disabled by the Configuration bits, BOREN<1:0> (FPOR<1:0>). When the Configuration bits are set to enable SBOREN, the default Reset state will be '1'.

REGISTER 8-4: INTCON2: INTERRUPT CONTROL REGISTER2

R/W-0	R-0, HSC	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ALTIVT:** Enable Alternate Interrupt Vector Table bit
1 = Uses Alternate Interrupt Vector Table
0 = Uses standard (default) vector table

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 8-11: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
NVMIE	—	AD1IE	U1TXIE	U1RXIE	—	—	T3IE
bit 15							bit 8

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-0
T2IE	CCP2IE	—	—	T1IE	CCP1IE	—	INT0IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NVMIE:** NVM Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **AD1IE:** A/D Conversion Complete Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 12 **U1TXIE:** UART1 Transmitter Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 11 **U1RXIE:** UART1 Receiver Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 10-9 **Unimplemented:** Read as ‘0’

bit 8 **T3IE:** Timer3 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 7 **T2IE:** Timer2 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 6 **CCP2IE:** Capture/Compare/PWM2 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 5-4 **Unimplemented:** Read as ‘0’

bit 3 **T1IE:** Timer1 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 2 **CCP1IE:** Capture/Compare/PWM1 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **INT0IE:** External Interrupt 0 Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 8-13: IEC2: INTERRUPT ENABLE CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	T3GIE	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5 **T3GIF:** Timer3 External Gate Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 4-0 **Unimplemented:** Read as ‘0’

REGISTER 8-14: IEC3: INTERRUPT ENABLE CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	BCL2IE(1)	SSP2IE(1)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2 **BCL2IE:** MSSP2 I^2C™ Bus Collision Interrupt Enable bit(1)
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **SSP2IF:** MSSP2 SPI/I^2C Event Interrupt Enable bit(1)
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **Unimplemented:** Read as ‘0’

Note 1: These bits are unimplemented on PIC24FXXKL10X and PIC24FXXKL20X devices.

REGISTER 8-18: IPC1: INTERRUPT PRIORITY CONTROL REGISTER 1

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T2IP2	T2IP1	T2IP0	—	CCP2IP2	CCP2IP1	CCP2IP0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **T2IP<2:0>:** Timer2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **CCP2IP<2:0>:** Capture/Compare/PWM2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

12.0 TIMER1

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Timers, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Timers"** (DS39704).

The Timer1 module is a 16-bit timer which can operate as a free-running, interval timer/counter, or serve as the time counter for a software-based Real-Time Clock (RTC). Timer1 is only reset on initial VDD power-on events. This allows the timer to continue operating as an RTC clock source through other types of device Reset.

Timer1 can operate in three modes:

- 16-Bit Timer
- 16-Bit Synchronous Counter
- 16-Bit Asynchronous Counter

Timer1 also supports these features:

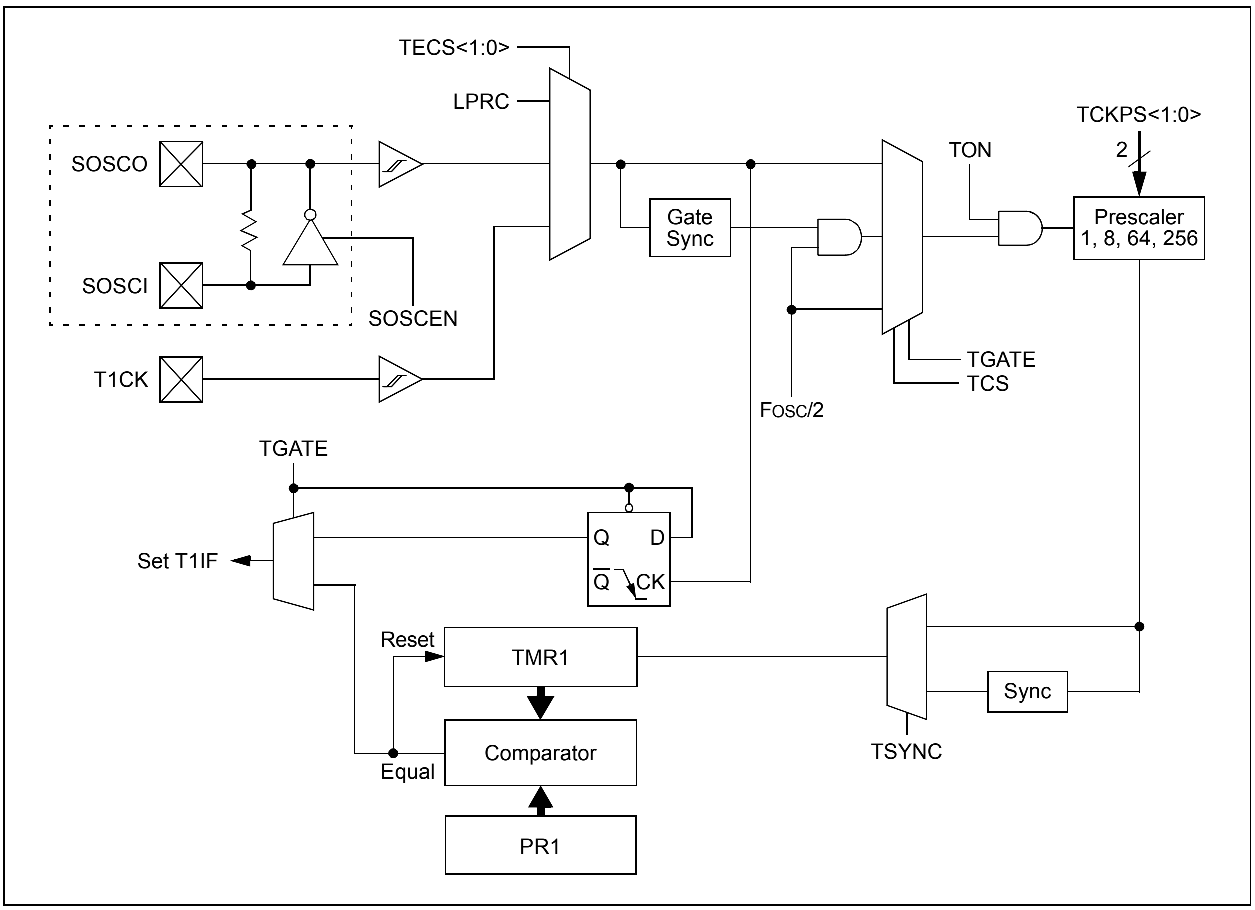
- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation During CPU Idle and Sleep modes
- Interrupt on 16-Bit Period Register Match or Falling Edge of External Gate Signal

Figure 12-1 illustrates a block diagram of the 16-bit Timer1 module.

To configure Timer1 for operation:

1. Set the TON bit (= 1).
2. Select the timer prescaler ratio using the TCKPS<1:0> bits.
3. Set the Clock and Gating modes using the TCS and TGATE bits.
4. Set or clear the TSYNC bit to configure synchronous or asynchronous operation.
5. Load the timer period value into the PR1 register.
6. If interrupts are required, set the Timer1 Interrupt Enable bit, T1IE. Use the Timer1 Interrupt Priority bits, T1IP<2:0>, to set the interrupt priority.

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



18.1 UART Baud Rate Generator (BRG)

The UART module includes a dedicated 16-bit Baud Rate Generator (BRG). The UxBRG register controls the period of a free-running, 16-bit timer. Equation 18-1 provides the formula for computation of the baud rate with BRGH = 0.

EQUATION 18-1: UARTx BAUD RATE WITH BRGH = 0(1)

$$\text{Baud Rate} = \frac{F_{CY}}{16 \cdot (\text{UxBRG} + 1)}$$

$$\text{UxBRG} = \frac{F_{CY}}{16 \cdot \text{Baud Rate}} - 1$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

Example 18-1 provides the calculation of the baud rate error for the following conditions:

- FCY = 4 MHz
- Desired Baud Rate = 9600

The maximum baud rate (BRGH = 0) possible is FCY/16 (for UxBRG = 0) and the minimum baud rate possible is FCY/(16 * 65536).

Equation 18-2 shows the formula for computation of the baud rate with BRGH = 1.

EQUATION 18-2: UARTx BAUD RATE WITH BRGH = 1(1)

$$\text{Baud Rate} = \frac{F_{CY}}{4 \cdot (\text{UxBRG} + 1)}$$

$$\text{UxBRG} = \frac{F_{CY}}{4 \cdot \text{Baud Rate}} - 1$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

The maximum baud rate (BRGH = 1) possible is FCY/4 (for UxBRG = 0) and the minimum baud rate possible is FCY/(4 * 65536).

Writing a new value to the UxBRG register causes the BRG timer to be reset (cleared). This ensures the BRG does not wait for a timer overflow before generating the new baud rate.

EXAMPLE 18-1: BAUD RATE ERROR CALCULATION (BRGH = 0)(1)

Desired Baud Rate = FCY/(16 (UxBRG + 1))

Solving for UxBRG Value:

UxBRG = ((FCY/Desired Baud Rate)/16) – 1
UxBRG = ((4000000/9600)/16) – 1
UxBRG = 25

Calculated Baud Rate = 4000000/(16 (25 + 1))
= 9615

Error = (Calculated Baud Rate – Desired Baud Rate)
Desired Baud Rate
= (9615 – 9600)/9600
= 0.16%

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

19.0 10-BIT HIGH-SPEED A/D CONVERTER

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the 10-Bit High-Speed A/D Converter, refer to the *“dsPIC33/PIC24 Family Reference Manual”*, **“10-Bit A/D Converter”** (DS39705).

The 10-bit A/D Converter has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 500 ksps
- Up to 12 analog input pins
- External voltage reference input pins
- Internal band gap reference input
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Two-word conversion result buffer
- Selectable Buffer Fill modes
- Four result alignment options
- Operation during CPU Sleep and Idle modes

Depending on the particular device, PIC24F16KL402 family devices implement up to 12 analog input pins, designated AN0 through AN4 and AN9 through AN15. In addition, there are two analog input pins for external voltage reference connections (VREF+ and VREF-). These voltage reference inputs may be shared with other analog input pins.

A block diagram of the A/D Converter is displayed in Figure 19-1.

To perform an A/D conversion:

1. Configure the A/D module:
    a) Configure port pins as analog inputs and/ or select band gap reference inputs (ANSA<3:0>, ANSB<15:12,4:0> and ANCFG<0>).
    b) Select the voltage reference source to match the expected range on analog inputs (AD1CON2<15:13>).
    c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
    d) Select the appropriate sample/conversion sequence (AD1CON1<7:5> and AD1CON3<12:8>).
    e) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
    f) Select interrupt rate (AD1CON2<5:2>).
    g) Turn on A/D module (AD1CON1<15>).
2. Configure A/D interrupt (if required):
    a) Clear the AD1IF bit.
    b) Select A/D interrupt priority.

REGISTER 22-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
HLVDEN	—	HLSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VDIR	BGVST	IRVST	—	HLVDL3	HLVDL2	HLVDL1	HLVDL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD is enabled
0 = HLVD is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **HLSIDL:** HLVD Stop in Idle Mode bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-8 **Unimplemented:** Read as ‘0’

bit 7 **VDIR:** Voltage Change Direction Select bit
1 = Event occurs when the voltage equals or exceeds the trip point (HLVDL<3:0>)
0 = Event occurs when the voltage equals or falls below the trip point (HLVDL<3:0>)

bit 6 **BGVST:** Band Gap Voltage Stable Flag bit
1 = Indicates that the band gap voltage is stable
0 = Indicates that the band gap voltage is unstable

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the internal reference voltage is stable and the High-Voltage Detect logic generates the interrupt flag at the specified voltage range
0 = Indicates that the internal reference voltage is unstable and the High-Voltage Detect logic will not generate the interrupt flag at the specified voltage range, and the HLVD interrupt should not be enabled

bit 4 **Unimplemented:** Read as ‘0’

bit 3-0 **HLVDL<3:0>:** High/Low-Voltage Detection Limit bits
1111 = External analog input is used (input comes from the HLVDIN pin)
1110 = Trip Point 14(1)
1101 = Trip Point 13(1)
1100 = Trip Point 12(1)
.
.
.
0000 = Trip Point 0(1)

Note 1: For the actual trip point, see **Section 26.0 “Electrical Characteristics”**.

TABLE 26-19: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Sym	Characteristic(1)	Min	Typ(2)	Max	Units	Conditions
OS50	FPLLI	PLL Input Frequency Range	4	—	8	MHz	ECPLL, HSPLL modes, -40°C ≤ TA ≤ +85°C
OS51	FSYS	PLL Output Frequency Range	16	—	32	MHz	-40°C ≤ TA ≤ +85°C
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	1	2	ms	
OS53	DCLK	CLKO Stability (Jitter)	-2	1	2	%	Measured over 100 ms period

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 26-20: INTERNAL RC OSCILLATOR ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Characteristic	Min	Typ	Max	Units	Conditions	
F20	FRC @ 8 MHz(1)	-2	—	+2	%	+25°C	3.0V ≤ VDD ≤ 3.6V
		-5	—	+5	%	-40°C ≤ TA ≤ +85°C	1.8V ≤ VDD ≤ 3.6V
		-10	—	+10	%	-40°C ≤ TA ≤ +125°C	1.8V ≤ VDD ≤ 3.6V
F21	LPRC @ 31 kHz(2)	-15	—	+15	%	-40°C ≤ TA ≤ +85°C	1.8V ≤ VDD ≤ 3.6V
		-25	—	+25	%	-40°C ≤ TA ≤ +125°C	1.8V ≤ VDD ≤ 3.6V

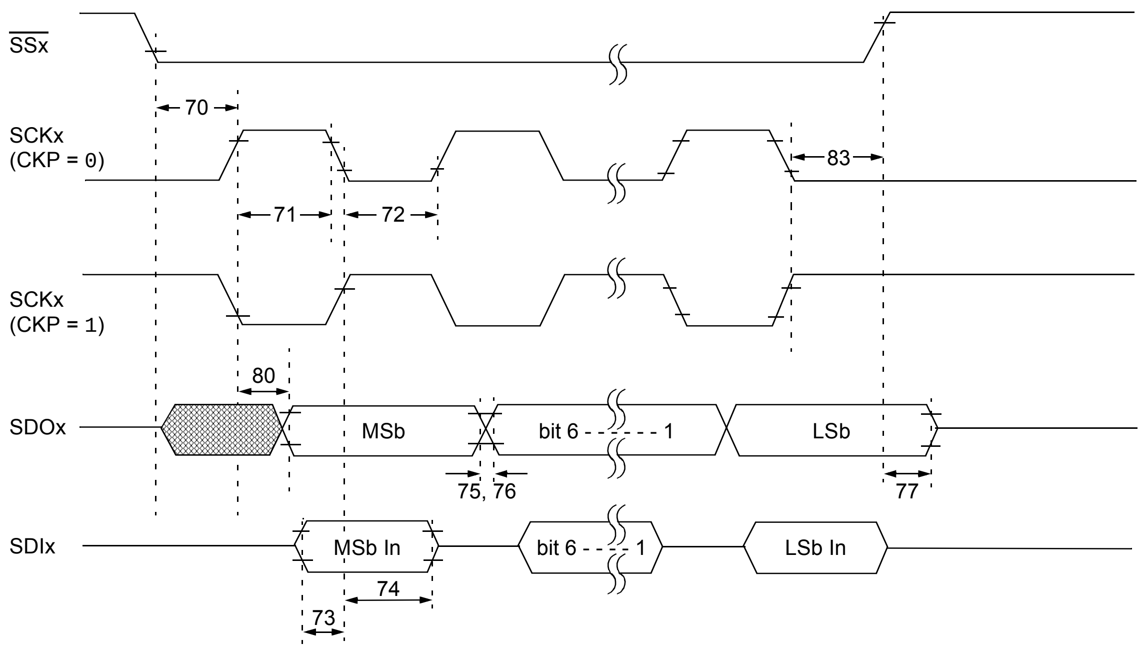
Note 1: The frequency is calibrated at +25°C and 3.3V. The OSCTUN bits can be used to compensate for temperature drift.

2: The change of LPRC frequency as VDD changes.

TABLE 26-21: INTERNAL RC OSCILLATOR SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions
	TFRC	FRC Start-up Time	—	5	—	μs	
	TLPRC	LPRC Start-up Time	—	70	—	μs	

FIGURE 26-9: EXAMPLE SPI SLAVE MODE TIMING (CKE = 0)



Note: Refer to Figure 26-3 for load conditions.

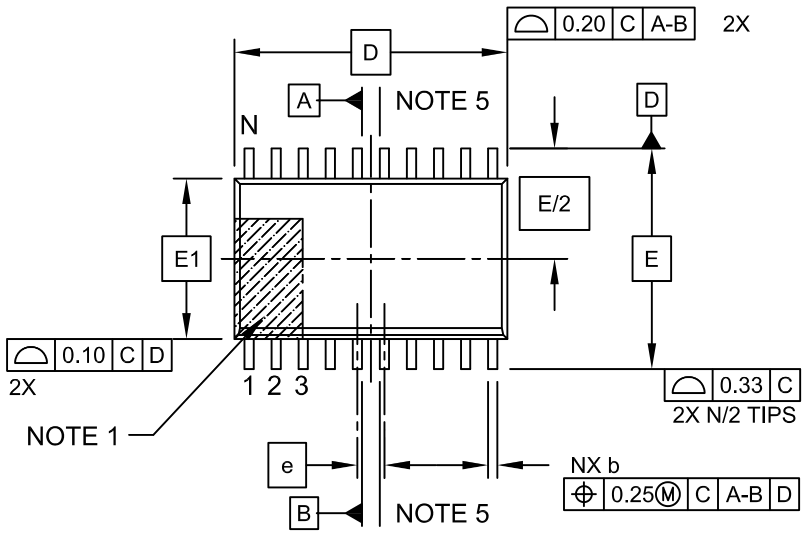
TABLE 26-29: EXAMPLE SPI MODE REQUIREMENTS (SLAVE MODE TIMING, CKE = 0)

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
70	TSSL2SCH, TSSL2SCL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input		3 TCY	—	ns	
70A	TSSL2WB	$\overline{SSx}$ to Write to SSPxBUF		3 TCY	—	ns	
71	TSCH	SCKx Input High Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TSCL	SCKx Input Low Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge		20	—	ns	
73A	TB2B	Last Clock Edge of Byte 1 to the First Clock Edge of Byte 2		1.5 TCY + 40	—	ns	**(Note 2)**
74	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge		40	—	ns	
75	TDOR	SDOx Data Output Rise Time		—	25	ns	
76	TDOF	SDOx Data Output Fall Time		—	25	ns	
77	TSSH2DOZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance		10	50	ns	
80	TSCH2DOV, TSCL2DOV	SDOx Data Output Valid after SCKx Edge		—	50	ns	
83	TSCH2SSH, TSCL2SSH	$\overline{SSx}$ ↑ after SCKx Edge		1.5 TCY + 40	—	ns	
	FSCK	SCKx Frequency		—	10	MHz	

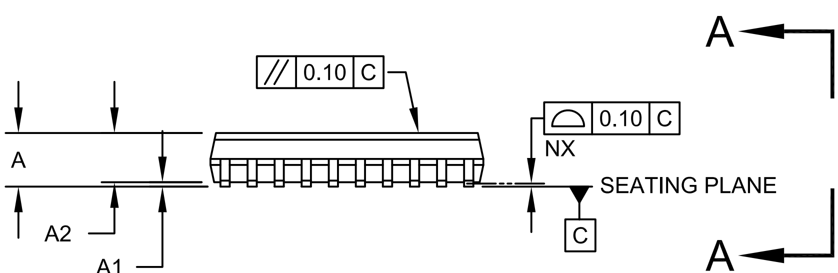
Note 1: Requires the use of Parameter 73A.
2: Only if Parameters 71A and 72A are used.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

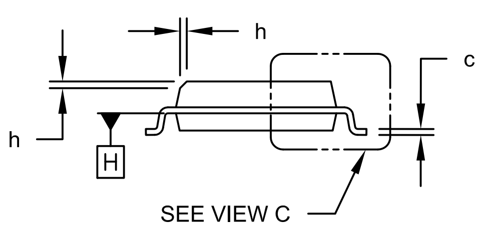
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

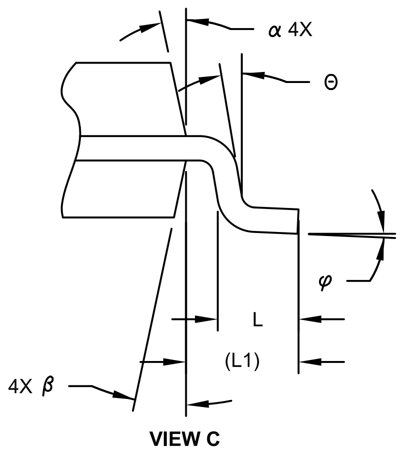


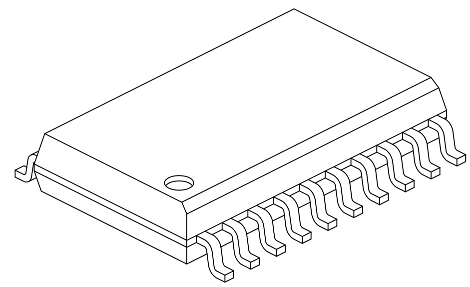
VIEW A-A

Microchip Technology Drawing C04-094C Sheet 1 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

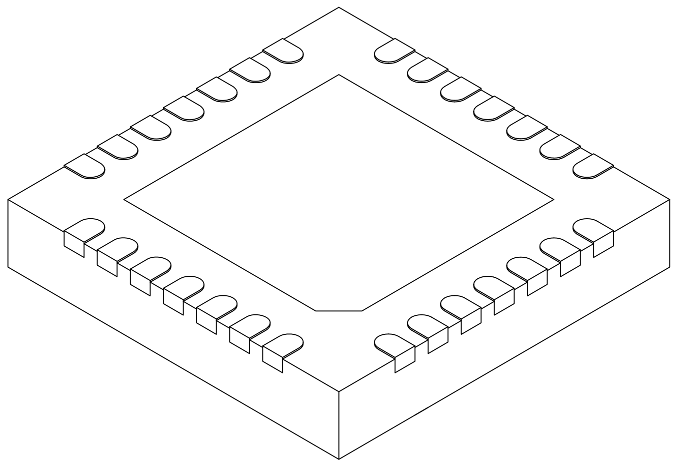
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

28-Lead Plastic Quad Flat, No Lead Package (MQ) – 5x5x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.15	3.25	3.35
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.15	3.25	3.35
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.35	0.40	0.45
Contact-to-Exposed Pad	K	0.20	-	-

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-140B Sheet 2 of 2

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
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